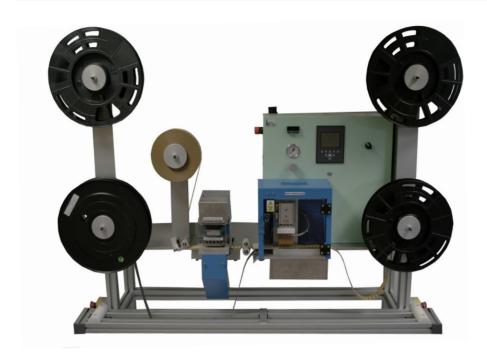
BGI100

Automatic glue tape lamination



Features & description

The BGI100 is an automatic glue tape lamination equipment (dimension 35mm width).

- Stand alone equipment with automatic hotmelt and chip feeding
- Screen touch interface (30 programs memorized)

Advantages

- Compact and easy with a throughput of 10 000 units per hour
- Easy adjustment of time, pressure and temperature parameters

Option BGI110a

■ BGI100a is the punch tool allowing to punch the hotmelt tape before lamination (glob top at the back of the chips)

Description

Width: 1500mmDepth: 560mmHeight: 1700mmWeight: 95kg

Throughput

Up to 10 000 units/hour

Facilities

Power: 100-240V AC

Frequency: 50-60Hz single phasePower consumption: 250W maximumPneumatic characteristics: 6 bars

Environmental conditions

Operating temperature: +10°C to +40°C

information: bgi.sales@bginge.com website: www.bginge.com